

Features

- Advanced Trench MOS Technology
- Low $R_{DS(ON)}$
- 100% EAS Guaranteed
- Green Device Available

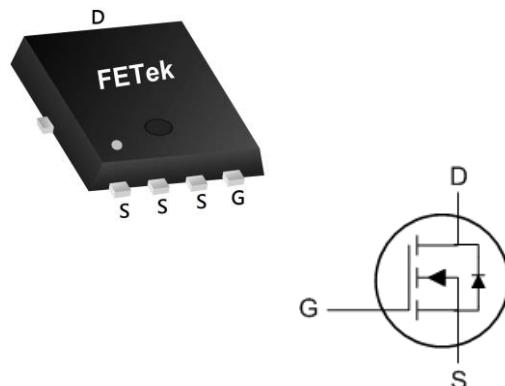
Product Summary

BVDSS	RDS(on)	ID
80V	5mΩ	98A

PRPAK5X6 Pin Configuration

Applications

- Power Tools.
- UPS
- Synchronous Rectifier in SMPS.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	98	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	62	A
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	16	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	13	A
I_{DM}	Pulsed Drain Current ²	250	A
EAS	Single Pulse Avalanche Energy ³	218	mJ
I_{AS}	Avalanche Current	66	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation ⁴	83	W
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	2.3	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	55	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	1.5	°C/W



FETek Technology Corp.

FKBA8070

N-Ch 80V Fast Switching MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	80	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=20\text{A}$	---	3.6	5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=20\text{A}$	---	5.1	7	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.2	1.7	2.3	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=64\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{\text{DS}}=64\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1.4	---	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=64\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=20\text{A}$	---	52.7	---	nC
Q_{gs}	Gate-Source Charge		---	7.8	---	
Q_{gd}	Gate-Drain Charge		---	12.5	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=64\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3\Omega$, $I_D=20\text{A}$	---	10	---	ns
T_r	Rise Time		---	37	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	42	---	
T_f	Fall Time		---	68	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2792	---	pF
C_{oss}	Output Capacitance		---	639	---	
C_{rss}	Reverse Transfer Capacitance		---	9.5	---	

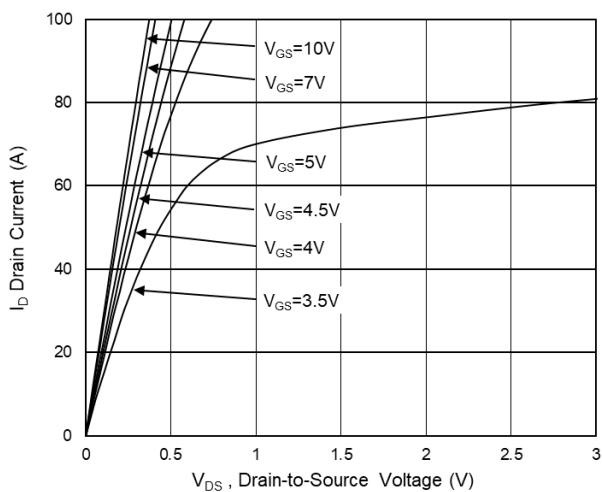
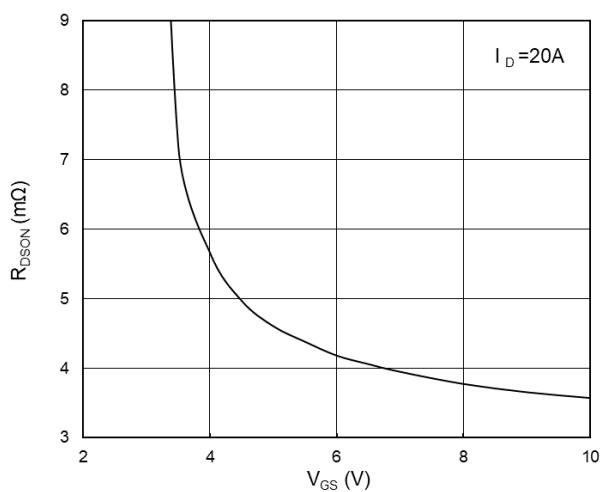
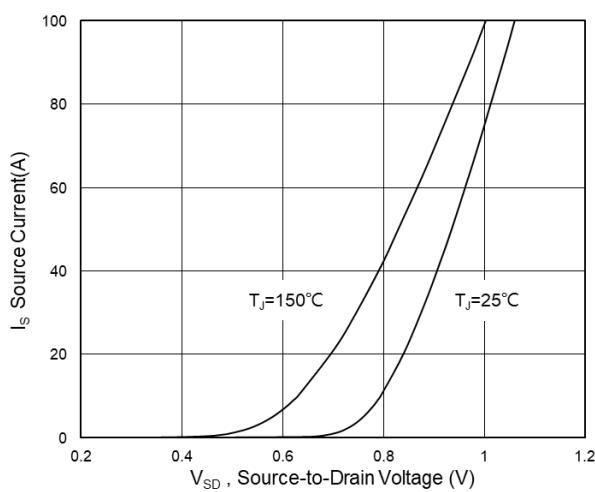
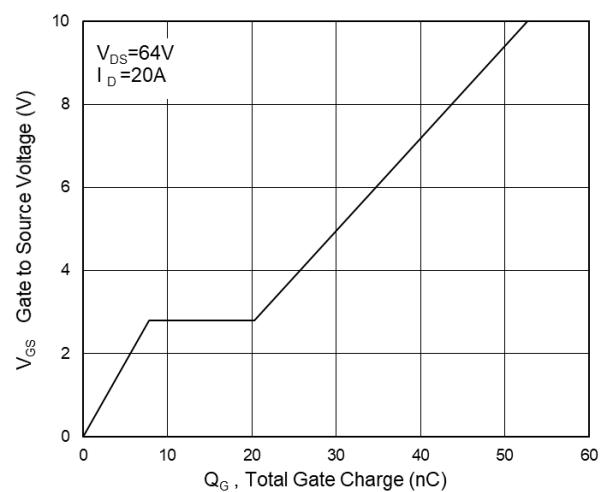
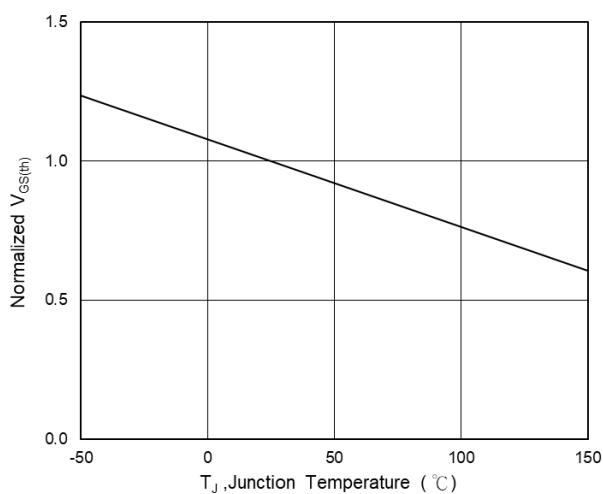
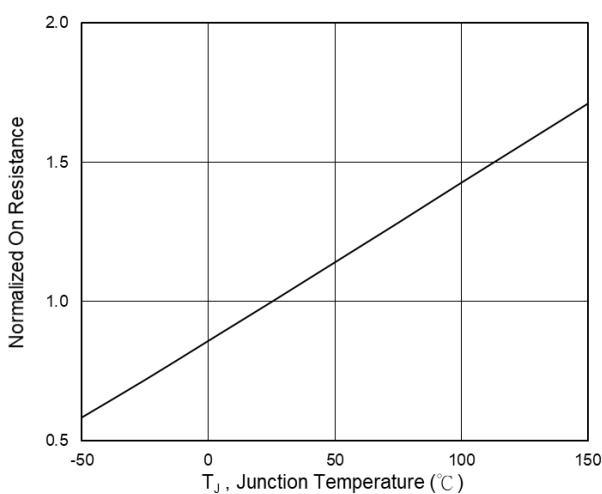
Diode Characteristics

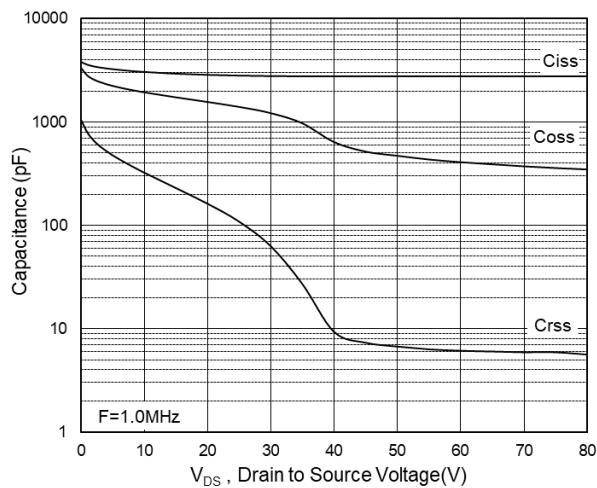
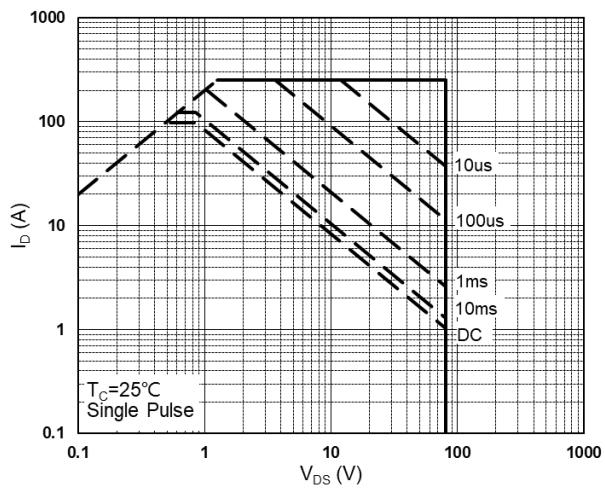
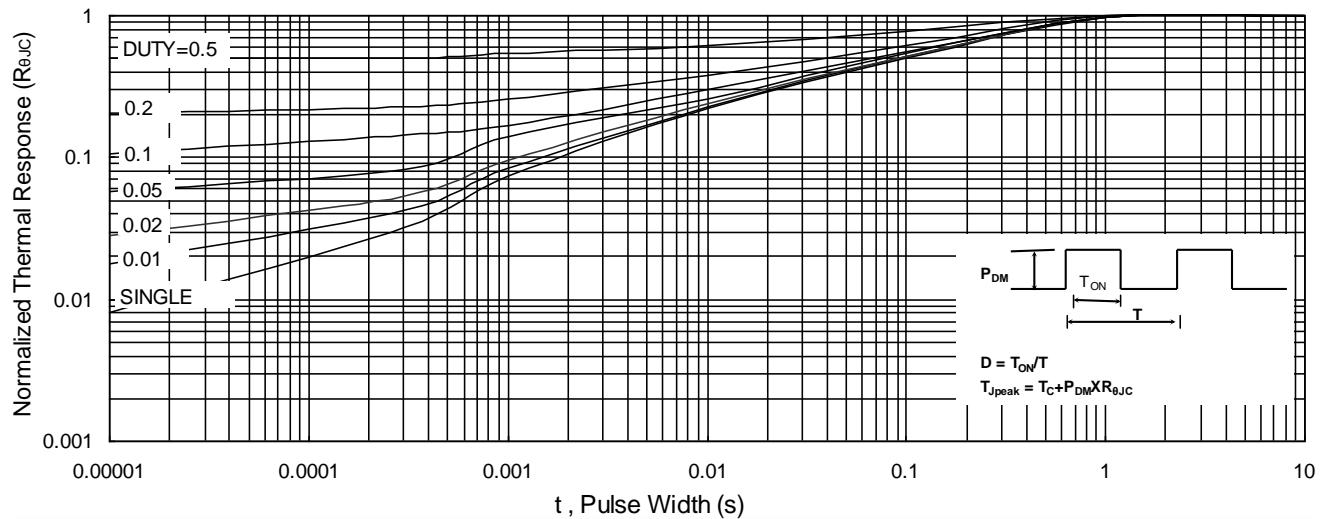
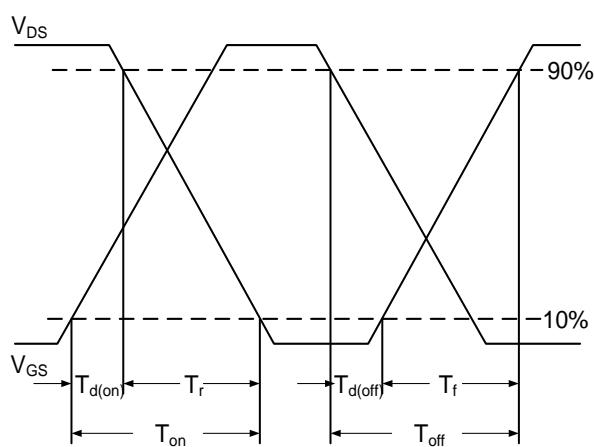
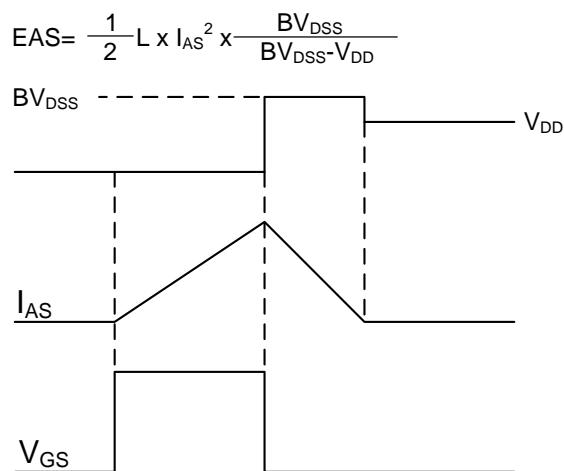
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	98	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=20\text{A}$, $di/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	23	---	nS
			---	22	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=66\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs G-S Voltage

Fig.3 Source Drain Forward Characteristics

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs T_J

Fig.6 Normalized $R_{DS(on)}$ vs T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Waveform